



Reply Under 37 CFR 1.116  
Expedited Procedure - Technology Center 1700

#1013 4/13/02  
(15) 11

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE  
FOR REFLOW SOLDERING

AMENDMENT UNDER 37 CFR 1.116

Assistant Commissioner for Patents  
Washington, D.C. 20231  
Box AF

RECEIVED  
APR 22 2002  
TC 1700

Dear Sir:

In response to the Official Action mailed on March 26, 2002, the Applicants request that the present application be amended as shown below.

IN THE CLAIMS:

Please rewrite claim 3 as shown below. A marked-up version of the amended claim is found on Attachment A at the end of this amendment.